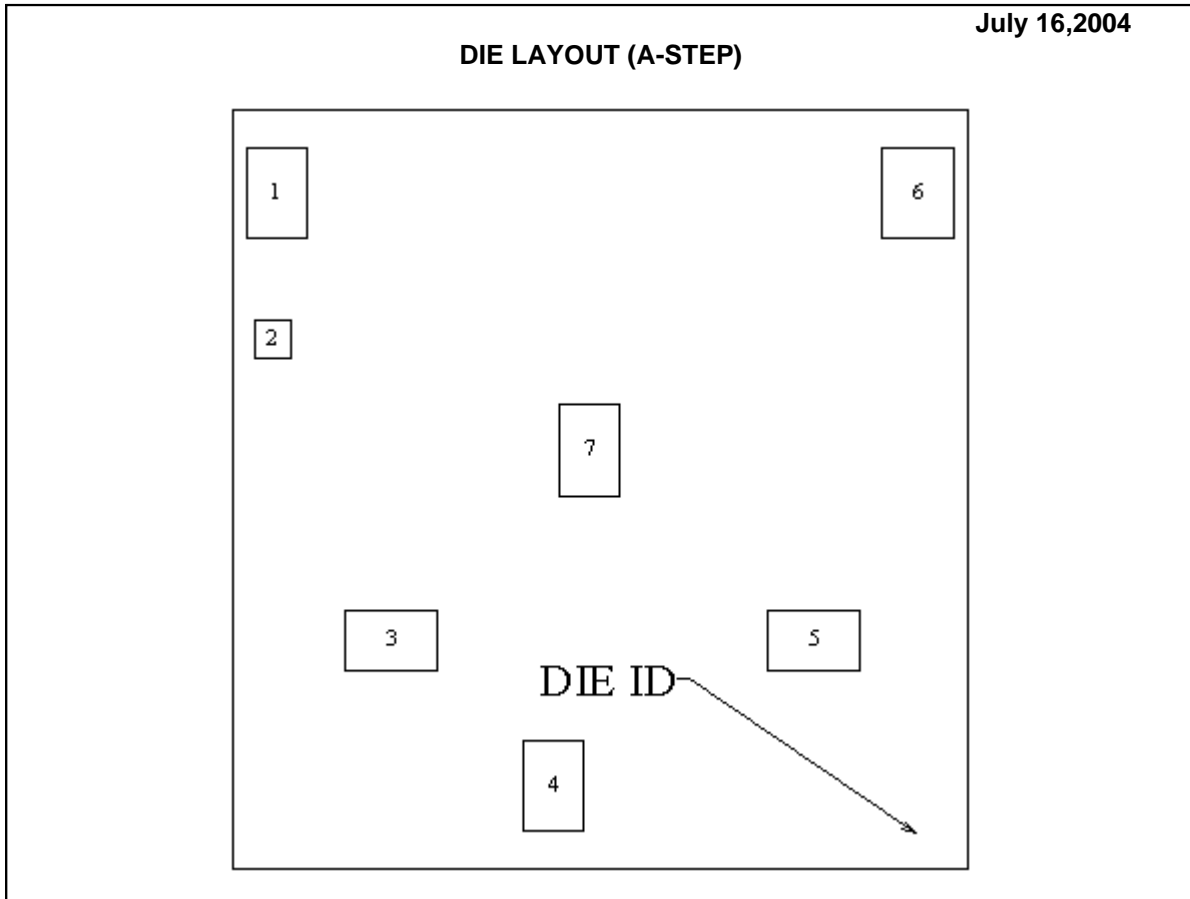


**LM350 MDC MWC  
3-AMP ADJUSTABLE REGULATORS**



**DIE/WAFER CHARACTERISTICS**

Fabrication Attributes		General Die Information	
Physical Die Identification	150A	Bond Pad Opening Size (min)	193 $\mu$ m x 295 $\mu$ m
Die Step	A	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	150mm	Back Side Metal	TINIAG
Die Size (Drawn)	2362 $\mu$ m x 2438 $\mu$ m 93.0mils x 96.0mils	Back Side Connection	OUTPUT
Thickness	330 $\mu$ m Nominal		
Min Pitch	468 $\mu$ m Nominal		

**Special Assembly Requirements:**

**Note: Actual die size is rounded to the nearest micron.**

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Die Bond Pad Coordinate Locations (A -Step)						
(Referenced to die center, coordinates in $\mu\text{m}$ ) NC = No Connection, N.U. = Not Used						
SIGNAL	PAD#	XY COORDINATES		PAD SIZE		
NAME	NUMBER	X	Y	X	Y	
ADJ	1	-1041	953	193	x	295
NC	2	-1054	484	117	x	119
OUTPUT	3	-673	-483	295	x	193
VIN	4	-152	-953	193	x	295
OUTPUT	5	686	-483	295	x	193
OUTPUT	6	1022	953	231	x	295
VIN	7	-33	127	193	x	295

**LM350 MDC MWC  
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**K**

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